




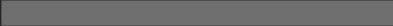



















# Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.010mm	3.5
4		Top Layer	Copper	0.035mm	
5		Dielectric 1	PP-017	0.130mm	4.3
6		Layer 1	Copper	0.035mm	
7		Dielectric 2	Core-025	0.203mm	4.6
8		Layer 2	Copper	0.035mm	
9		Dielectric 3.1	PP-017	0.130mm	4.3
10		Dielectric 3.2	PP-017	0.130mm	4.3
11		Layer 3	Copper	0.035mm	
12		Dielectric 4	Core-025	0.203mm	4.6
13		Layer 4	Copper	0.035mm	
14		Dielectric 5.1	PP-017	0.130mm	4.3
15		Dielectric 5.2	PP-017	0.130mm	4.3
16		Layer 5	Copper	0.035mm	
17		Dielectric 6	Core-025	0.203mm	4.6
18		Layer 6	Copper	0.035mm	
19		Dielectric 7	PP-017	0.130mm	4.3
20		Bottom Layer	Copper	0.035mm	
21		Bottom Solder	Solder Resist	0.010mm	3.5
22		Bottom Overlay			
23		Bottom Paste			
Height : 1.687mm					